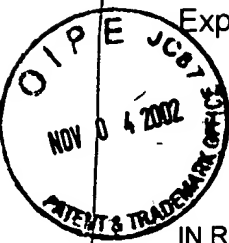


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Setho Sing Fee *et al.*

APPLICATION No.: 09/944,246

FILED: 30 August 2001

FOR: **PACKAGED MICROELECTRONIC
DEVICES AND METHODS OF FORMING
SAME**

EXAMINER: Tu-Tu Ho

ART UNIT: 2818

CONF. No: 1798

PATENT
G. J. J. J.
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TECHNOLOGY CENTER 2800

Amendment Under 37 C.F.R. § 1.111

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The present communication responds to the Office Action dated 3 July 2002 in the above-identified application. Please amend the application as follows. The attached Appendix presents a marked-up version of the changes made to the specification and claims by the current amendment.

In the Specification:

Please amend paragraph 0052 to read as follows:

The electrical connector 96 has a thickness which spaces the first and second subassemblies 10a-b from one another, defining an intercomponent gap 94 therebetween. If so desired, this intercomponent gap 94 can be filled with an underfill material or the like. This is not believed to be necessary, though, and leaving the intercomponent gap 94 exposed to the ambient environment may further facilitate cooling of the die 60b via its exposed back surface 66. An outer covering 98 of an electrically insulative material may be applied over the front contacts 36b of the upper subassembly 10b to avoid any inadvertent electrical short circuits. Alternatively, a third microelectronic device (which may be another microelectronic device assembly 10 such